

2SK2606

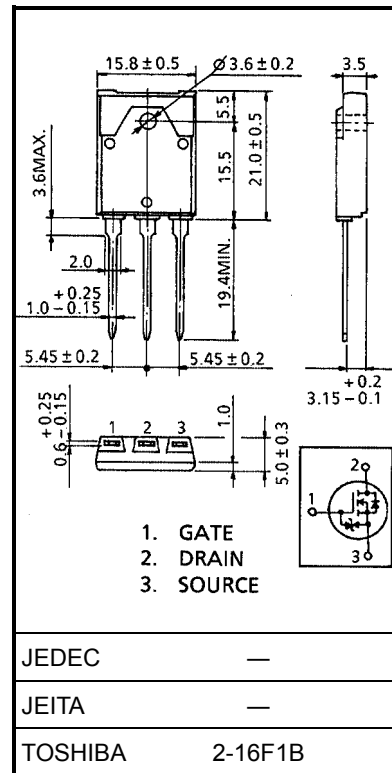
DC-DC Converter, Relay Drive and Motor Drive Applications

Unit: mm

- Low drain-source ON resistance : $R_{DS(ON)} = 1.0 \Omega$ (typ.)
- High forward transfer admittance : $|Y_{fs}| = 7.0 \text{ S}$ (typ.)
- Low leakage current : $I_{DSS} = 100 \mu\text{A}$ (max) ($V_{DS} = 640 \text{ V}$)
- Enhancement-mode : $V_{th} = 2.0 \sim 4.0 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$)

Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	800	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	800	V
Gate-source voltage		V_{GSS}	± 30	V
Drain current	DC (Note 1)	I_D	8	A
	Pulse (Note 1)	I_{DP}	24	A
Drain power dissipation ($T_c = 25^\circ\text{C}$)		P_D	85	W
Single pulse avalanche energy (Note 2)		E_{AS}	883	mJ
Avalanche current		I_{AR}	8	A
Repetitive avalanche energy (Note 3)		E_{AR}	8.5	mJ
Channel temperature		T_{ch}	150	$^\circ\text{C}$
Storage temperature range		T_{stg}	$-55 \sim 150$	$^\circ\text{C}$



Weight: 5.8 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th(ch-c)}$	1.47	$^\circ\text{C} / \text{W}$
Thermal resistance, channel to ambient	$R_{th(ch-a)}$	41.6	$^\circ\text{C} / \text{W}$

Note 1: Please use devices on condition that the channel temperature is below 150°C .

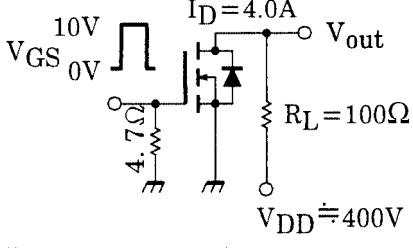
Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 25.0 \text{ mH}$, $I_{AR} = 8 \text{ A}$, $R_G = 25 \Omega$

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

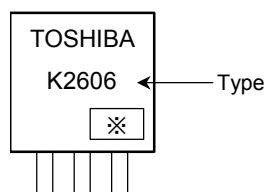
Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	—	—	± 10	μA
Gate-source breakdown voltage		$V_{(BR)GSS}$	$I_G = \pm 10 \mu\text{A}, V_{DS} = 0 \text{ V}$	± 30	—	—	V
Drain cut-off current		I_{DSS}	$V_{DS} = 640 \text{ V}, V_{GS} = 0 \text{ V}$	—	—	100	μA
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	800	—	—	V
Gate threshold voltage		V_{th}	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$	2.0	—	4.0	V
Drain-source ON resistance		$R_{DS(ON)}$	$V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}$	—	1.0	1.2	Ω
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 15 \text{ V}, I_D = 4 \text{ A}$	3.0	7.0	—	S
Input capacitance		C_{iss}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	—	2160	—	pF
Reverse transfer capacitance		C_{rss}		—	45	—	
Output capacitance		C_{oss}		—	200	—	
Switching time	Rise time	t_r	 $I_D = 4.0 \text{ A}$ $V_{GS} = 10 \text{ V}, 0 \text{ V}$ $R_L = 100 \Omega$ $V_{DD} \approx 400 \text{ V}$ Duty $\leq 1\%$, $t_w = 10 \mu\text{s}$	—	25	—	ns
	Turn-on time	t_{on}		—	60	—	
	Fall time	t_f		—	25	—	
	Turn-off time	t_{off}		—	110	—	
Total gate charge (gate-source plus gate-drain)		Q_g	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 8 \text{ A}$	—	68	—	nC
Gate-source charge		Q_{gs}		—	38	—	
Gate-drain ("miller") Charge		Q_{gd}		—	30	—	

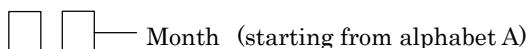
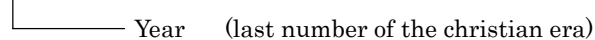
Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	—	—	—	8	A
Pulse drain reverse current (Note 1)	I_{DRP}	—	—	—	24	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = 8 \text{ A}, V_{GS} = 0 \text{ V}$	—	—	-1.9	V
Reverse recovery time	t_{rr}	$I_{DR} = 8 \text{ A}, V_{GS} = 0 \text{ V}, dI_{DR} / dt = 100 \text{ A} / \mu\text{s}$	—	1500	—	ns
Reverse recovery charge	Q_{rr}		—	19	—	μC

Marking



※ Lot Number

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